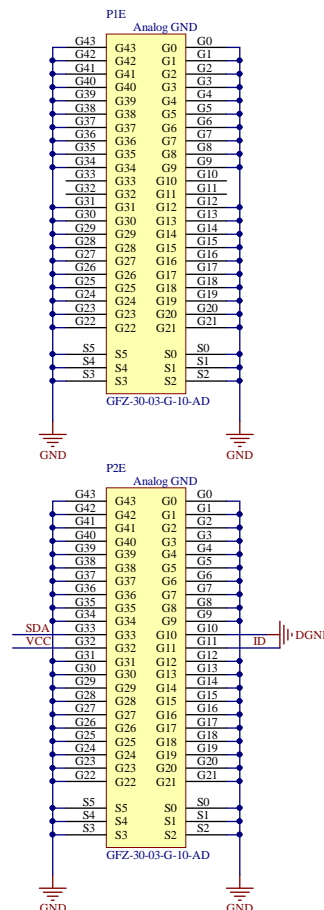
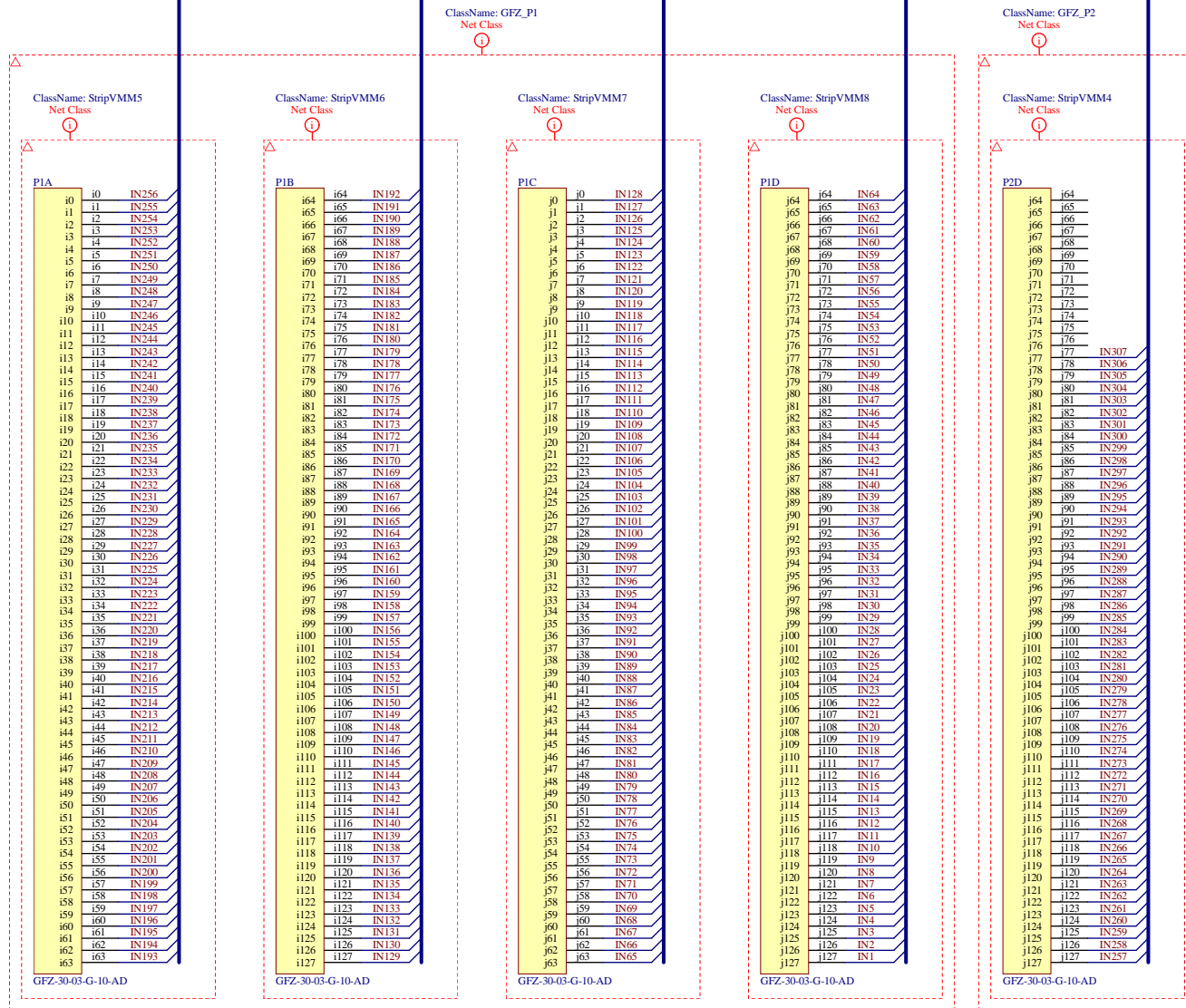
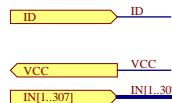


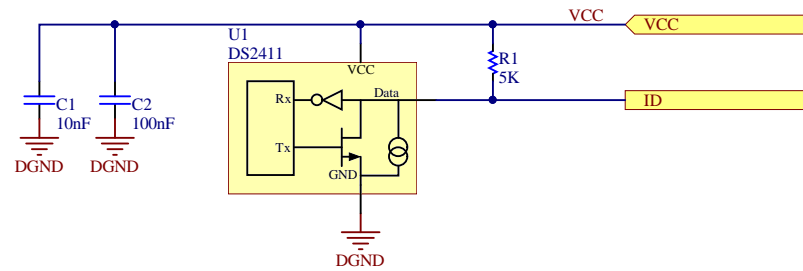
Project/Equipment		sTGC_Strip_AB_307Ch	
Document	Designer	Alam Toro	
	Drawn by	Alam Toro	09/01/2015
	Check by	-	-
	Last Mod.	Alam Toro	30/05/2017
	File	sTGC_Strip_AB_307Ch_02.SchDoc	
Print Date		07/06/2017 15:24:46	Sheet 2 of 4
Size		A4	Rev 3

**sTGC\_Strip\_AB\_307Ch**  
**Detector Edge**

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**EDA-XXXXX-VX-X**

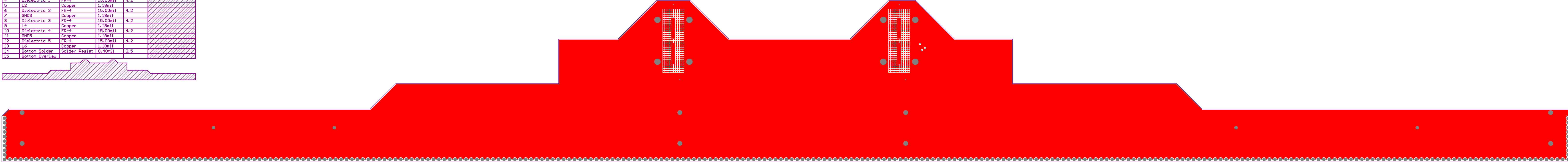




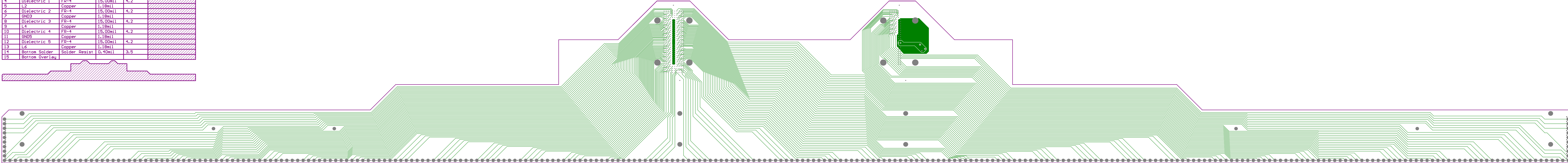
Project/Equipment		sTGC_Strip_AB_307Ch				
<div><div>sTGC</div><div>CERN</div></div>	<div>sTGC_Strip_AB_307Ch</div> <div>Wire Connector</div>		Designer	Alam Toro		
			Drawn by	Alam Toro	09/01/2015	
			Check.by	-	-	
			Last Mod.	Alam Toro	30/05/2017	
			File	sTGC_Strip_AB_307Ch_04.SchDoc		
		Print Date	07/06/2017 15:24:47	Sheet	4 of 4	
European Organization for Nuclear Research CH-1211 Genève 23 - Switzerland		EDA-XXXXX-VX-X			Size	Rev
					A4	3



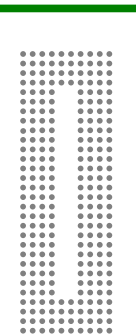
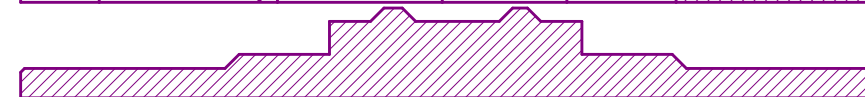
Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				[Hatched]
2	Top Solder	Solder Resist	0.40mil	3.5	
3	L1	Copper	1.18mil		[Hatched]
4	Dielectric 1	FR-4	15.00mil	4.2	
5	L2	Copper	1.18mil		[Hatched]
6	Dielectric 2	FR-4	15.00mil	4.2	
7	GND3	Copper	1.18mil		[Hatched]
8	Dielectric 3	FR-4	15.00mil	4.2	
9	L4	Copper	1.18mil		[Hatched]
10	Dielectric 4	FR-4	15.00mil	4.2	
11	GND5	Copper	1.18mil		[Hatched]
12	Dielectric 5	FR-4	15.00mil	4.2	
13	L6	Copper	1.18mil		[Hatched]
14	Bottom Solder	Solder Resist	0.40mil	3.5	
15	Bottom Overlay				[Hatched]



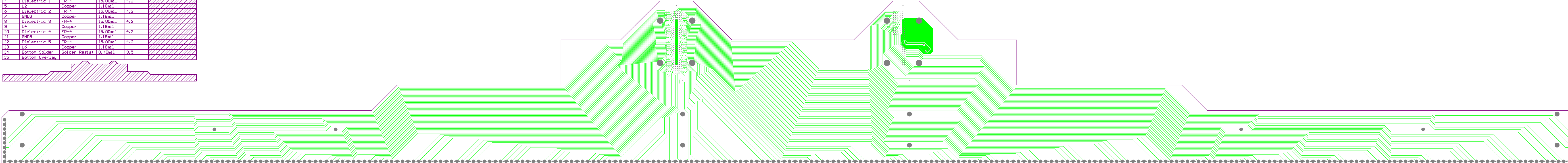
Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				[Hatched]
2	Top Solder	Solder Resist	0.40mil	3.5	
3	L1	Copper	1.18mil		[Hatched]
4	Dielectric 1	FR-4	15.00mil	4.2	
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7	GND3	Copper	1.18mil		[Hatched]
8	Dielectric 3	FR-4	15.00mil	4.2	
9	L4	Copper	1.18mil		[Hatched]
10	Dielectric 4	FR-4	15.00mil	4.2	
11	GND5	Copper	1.18mil		[Hatched]
12	Dielectric 5	FR-4	15.00mil	4.2	
13	L6	Copper	1.18mil		[Hatched]
14	Bottom Solder	Solder Resist	0.40mil	3.5	
15	Bottom Overlay				[Hatched]



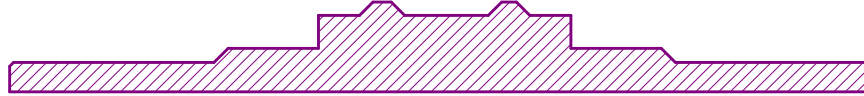
Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				[Hatched]
2	Top Solder	Solder Resist	0.40mil	3.5	
3	L1	Copper	1.18mil		[Hatched]
4	Dielectric 1	FR-4	15.00mil	4.2	
5	L2	Copper	1.18mil		[Hatched]
6	Dielectric 2	FR-4	15.00mil	4.2	
7	GND3	Copper	1.18mil		[Hatched]
8	Dielectric 3	FR-4	15.00mil	4.2	
9	L4	Copper	1.18mil		[Hatched]
10	Dielectric 4	FR-4	15.00mil	4.2	
11	GND5	Copper	1.18mil		[Hatched]
12	Dielectric 5	FR-4	15.00mil	4.2	
13	L6	Copper	1.18mil		[Hatched]
14	Bottom Solder	Solder Resist	0.40mil	3.5	
15	Bottom Overlay				[Hatched]



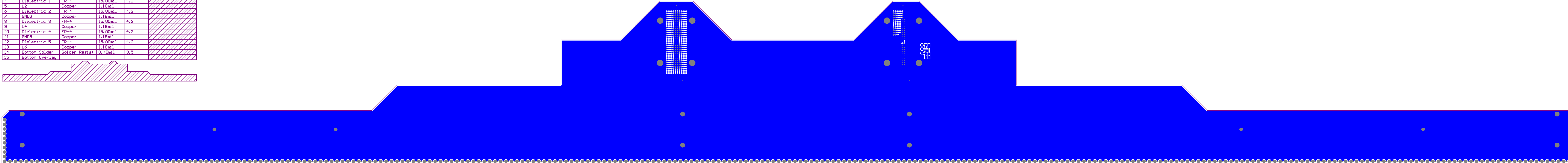
Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				[Hatched]
2	Top Solder	Solder Resist	0.40mil	3.5	
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13	L6	Copper	1.18mil		[Hatched]
14	Bottom Solder	Solder Resist	0.40mil	3.5	
15	Bottom Overlay				[Hatched]



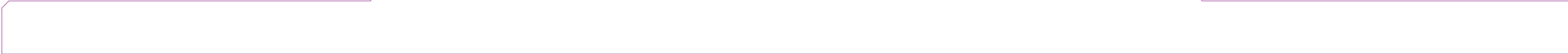
Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				[Hatched]
2	Top Solder	Solder Resist	0.40mil	3.5	
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5	L2	Copper	1.18mil		[Hatched]
6	Dielectric 2	FR-4	15.00mil	4.2	
7	GND3	Copper	1.18mil		[Hatched]
8	Dielectric 3	FR-4	15.00mil	4.2	
9	L4	Copper	1.18mil		[Hatched]
10	Dielectric 4	FR-4	15.00mil	4.2	
11	GND5	Copper	1.18mil		[Hatched]
12	Dielectric 5	FR-4	15.00mil	4.2	
13	L6	Copper	1.18mil		[Hatched]
14	Bottom Solder	Solder Resist	0.40mil	3.5	
15	Bottom Overlay				[Hatched]



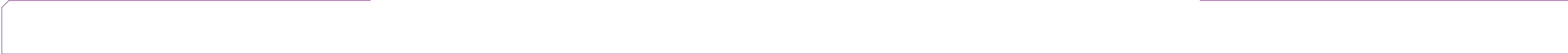
Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				[Hatched]
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15	Bottom Overlay				[Hatched]



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13	L6	Copper	1.18mil		[Hatched]
14	Bottom Solder	Solder Resist	0.40mil	3.5	
15	Bottom Overlay				[Hatched]





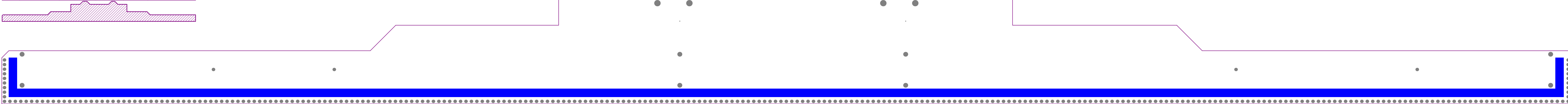
Layer	Name	Material	Thickness	Constant	Board Layer Stack
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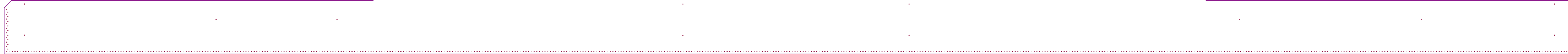


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13	L6	Copper	1.18mil		[Hatched]
14	Bottom Solder	Solder Resist	0.40mil	3.5	
15	Bottom Overlay				[Hatched]



Symbol	Hit Count	Finished Hole Size	Plated	Hole Type	Physical Length
■	3	15.75mil (0.400mm)	PTH	Round	-
★	4	65.00mil (1.651mm)	NPTH	Round	-
⊗	4	78.74mil (2.000mm)	NPTH	Slot	253.43mil (6.437mm)
⊙	8	78.74mil (2.000mm)	NPTH	Round	-
○	8	110.24mil (2.800mm)	NPTH	Round	-
○	307	11.81mil (0.300mm)	PTH	Round	-
✕	307	53.15mil (1.350mm)	PTH	Round	-
◇	389	10.08mil (0.256mm)	PTH	Round	-
	1030 Total				

Slot definitions : Routed Path Length = Calculated from tool start centre position to tool end centre position.  
Physical Length = Routed Path Length + Tool Size = Slot length as defined in the PCB layout



Layer	Name	Material	Thickness	Constant	Board Layer Stack
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